



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-20
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
BTA24-800CWRG	7BVT*248SBL1	A	SH1A	2016-05-20
	Amount	UoM	Unit type	ST ECOPACK Grade
	1900.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2,15.5,4.5	3	Through-hole	
Comment	TO 220 I CLIP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)
7c-1	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7BVT*248SBL1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	15.865	mg	supplier	die	Silicon (Si)	7440-21-3		14.11	mg	889379	7426
				supplier	metallization	Nickel (Ni)	7440-02-0		0.179	mg	11283	94
				supplier	metallization	Gold (Au)	7440-57-5		0.039	mg	2458	21
				supplier	glass coating	Glass : Aluminium Oxide	1344-28-1		0.114	mg	7186	60
				supplier	glass coating	Lead-Borate Glass	65997-18-4	7c-I-Electrical and e	1.022	mg	64419	538
				supplier	back side metallization	Gold (Au)	7440-57-5		0.018	mg	1134	9
Leadframe + Slug	Copper & its alloys	1635.21	mg	supplier	back side metallization	Nickel (Ni)	7440-02-0		0.383	mg	24141	202
				supplier	alloy	Copper (Cu)	7440-50-8		1616.944	mg	988830	851023
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		3.249	mg	1987	1710
				supplier	alloy	Cobalt (Co)	7440-48-4		4.549	mg	2782	2394
				supplier	metallization	Nickel (Ni)	7440-02-0		10.468	mg	6402	5509
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	9.561	mg	925019	5032
Soft solder	Solder	10.336	mg	JIG R	solder	Silver (Ag)	7440-22-4		0.517	mg	50019	272
				supplier	solder	Tin (Sn)	7440-31-5		0.258	mg	24961	136
				supplier	solder	Copper (Cu)	7440-50-8		31.625	mg	1000000	16645
Clip	Other inorganic materials	31.625	mg	supplier	clip	Copper (Cu)	7440-50-8		31.625	mg	1000000	16645
Encapsulation	Other Organic Materials	111.45	mg	supplier	mold compound	Silica, vitreous	60676-86-0		82.696	mg	742001	43524
				supplier	mold compound	Phenol resin	9003-35-4		5.573	mg	50004	2933
				supplier	mold compound	Carbon black	1333-86-4		0.891	mg	7995	469
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		12.259	mg	109996	6452
				supplier	mold compound	Others	Proprietary		10.031	mg	90004	5279
Connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314	mg	1000000	3323
Subelement		89.2	mg	supplier	Ceramic isolator	Aluminium Oxide	1344-28-1		87.559	mg	981603	46084
				supplier	Ceramic isolator	Nickel (Ni)	7440-02-0		1.07	mg	11996	563
				supplier	Ceramic isolator	Gold (Au)	7440-57-5		0.571	mg	6401	302